

Title (en)

Thermal barrier coating system and method for coating a component

Title (de)

Wärmesperrenbeschichtungssystem und Verfahren zur Beschichtung eines Bauteils

Title (fr)

Système de revêtement de barrière thermique et procédé pour le revêtement d'un composant

Publication

EP 1939316 A1 20080702 (EN)

Application

EP 07122214 A 20071204

Priority

US 61298706 A 20061219

Abstract (en)

A thermal barrier coating system (12) for using with a component (10) is provided. The thermal barrier coating system (12) includes a roughened high-velocity oxy-fuel (HVOF) layer applied to an outer surface of the component. The thermal barrier coating system (12) further includes a ceramic coating (18) applied to the roughened HVOF layer, the ceramic coating including a plurality of dense vertically cracked (DVC) ceramic layers.

IPC 8 full level

C23C 4/08 (2006.01); **C23C 4/02** (2006.01); **C23C 4/10** (2006.01); **C23C 4/12** (2006.01); **C23C 4/18** (2006.01); **C23C 28/00** (2006.01)

CPC (source: EP US)

C23C 4/02 (2013.01 - EP US); **C23C 4/073** (2016.01 - EP US); **C23C 4/10** (2013.01 - EP US); **C23C 4/129** (2016.01 - EP US); **C23C 28/321** (2013.01 - EP US); **C23C 28/3215** (2013.01 - EP US); **C23C 28/345** (2013.01 - EP US); **C23C 28/3455** (2013.01 - EP US); **Y02T 50/60** (2013.01 - US); **Y10T 428/12535** (2015.01 - EP US)

Citation (search report)

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Designated extension state (EPC)

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